



## Product Change Notification - SYST-22NWSA404

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**Date:**

28 Aug 2019

**Product Category:**

Memory

**Affected CPNs:**



**Notification subject:**

Data Sheet - 25AA256/25LC256 Device Data Sheet Document Revision

**Notification text:**

SYST-22NWSA404

Microchip has released a new Product Documents for the 25AA256/25LC256 Device Data Sheet of devices. If you are using one of these devices please read the document located at [25AA256/25LC256 Device Data Sheet](#).

**Notification Status:** Final

**Description of Change:**

- 1) Revise Product ID System, packages and notes.
- 2) Clarified Extended E-Temp description
- 3) Update RoHS compliant description
- 4) Update PDIP package drawing.

**Impacts to Data Sheet:** None

**Reason for Change:** To Improve Manufacturability

**Change Implementation Status:** Complete

**Date Document Changes Effective:** 28 Aug 2019

**NOTE:** Please be advised that this is a change to the document only the product has not been changed.

**Markings to Distinguish Revised from Unrevised Devices:** N/A

**Attachment(s):**

[25AA256/25LC256 Device Data Sheet](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

25AA256-E/MF  
25AA256-E/P  
25AA256-E/SM  
25AA256-E/SN  
25AA256-E/ST  
25AA256-I/FC16KB22  
25AA256-I/MF  
25AA256-I/P  
25AA256-I/S16K  
25AA256-I/SM  
25AA256-I/SMRVA  
25AA256-I/SN  
25AA256-I/ST  
25AA256-I/W16K  
25AA256-I/WM16KB21  
25AA256-I/WM16KB24  
25AA256-I/WNBG16K  
25AA256/S0816K  
25AA256/S08RVA  
25AA256/S1116K  
25AA256/S16K  
25AA256/W0816K  
25AA256/W1116K  
25AA256/W16K  
25AA256/WF1116K  
25AA256/WF16K  
25AA256/WNBGRVA  
25AA256T-E/MF  
25AA256T-E/SM  
25AA256T-E/SN  
25AA256T-E/ST  
25AA256T-I/MF  
25AA256T-I/SM  
25AA256T-I/SMRVA  
25AA256T-I/SN  
25AA256T-I/SN16KVAO  
25AA256T-I/SNB31  
25AA256T-I/ST  
25AA256T-I/ST16KV13  
25AA256T-I/ST16KVAO  
25AA256X-I/ST  
25AA256XT-I/ST  
25LC256-E/MF  
25LC256-E/P  
25LC256-E/SM  
25LC256-E/SM16KVAO

25LC256-E/SN  
25LC256-E/SN16KV09  
25LC256-E/SN16KV17  
25LC256-E/SN16KV22  
25LC256-E/SN16KVAO  
25LC256-E/ST  
25LC256-E/ST16KVAO  
25LC256-E/W16K  
25LC256-E/WMNBG16K  
25LC256-H/SN  
25LC256-I/MF  
25LC256-I/MF16K  
25LC256-I/P  
25LC256-I/SM  
25LC256-I/SN  
25LC256-I/SNRVB  
25LC256-I/ST  
25LC256-M/MF  
25LC256T-E/MF  
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25LC256T-E/SM16KV01  
25LC256T-E/SM16KV20  
25LC256T-E/SM16KVAO  
25LC256T-E/SN  
25LC256T-E/SN16KV04  
25LC256T-E/SN16KV07  
25LC256T-E/SN16KV09  
25LC256T-E/SN16KV10  
25LC256T-E/SN16KV15  
25LC256T-E/SN16KV16  
25LC256T-E/SN16KV17  
25LC256T-E/SN16KV18  
25LC256T-E/SN16KV19  
25LC256T-E/SN16KV21  
25LC256T-E/SN16KV23  
25LC256T-E/SN16KVAO  
25LC256T-E/ST  
25LC256T-E/ST16KV08  
25LC256T-E/ST16KV14  
25LC256T-E/ST16KV22  
25LC256T-E/ST16KV23  
25LC256T-E/ST16KV24  
25LC256T-E/ST16KV25  
25LC256T-E/ST16KV27  
25LC256T-E/ST16KVAO  
25LC256T-H/DT16KV11  
25LC256T-H/SN  
25LC256T-I/MF  
25LC256T-I/MF16K

25LC256T-I/SM  
25LC256T-I/SM16KV03  
25LC256T-I/SN  
25LC256T-I/SN16KV08  
25LC256T-I/SNRVB  
25LC256T-I/ST  
25LC256T-I/STA31  
25LC256T-I/STRVA  
25LC256T-M/MF  
25LC256X-E/ST  
25LC256X-I/ST  
25LC256XT-E/ST  
25LC256XT-I/ST

## 256K SPI Bus Serial EEPROM

### Device Selection Table

| Part Number | Vcc Range | Page Size | Temp. Ranges | Packages          |
|-------------|-----------|-----------|--------------|-------------------|
| 25LC256     | 2.5-5.5V  | 64 Byte   | I, E         | P, SN, SM, ST, MF |
| 25AA256     | 1.8-5.5V  | 64 Byte   | I, E         | P, SN, SM, ST, MF |

### Features

- Max. Clock 10 MHz
- Low-Power CMOS Technology:
  - Max. Write Current: 5 mA at 5.5V, 10 MHz
  - Read Current: 6 mA at 5.5V, 10 MHz
  - Standby Current: 1  $\mu$ A at 5.5V
- 32,768 x 8-Bit Organization
- 64-Byte Page
- Self-Timed Erase and Write Cycles (5 ms max.)
- Block Write Protection:
  - Protect none, 1/4, 1/2 or all of array
- Built-In Write Protection:
  - Power-on/off data protection circuitry
  - Write enable latch
  - Write-protect pin
- Sequential Read
- High Reliability:
  - Endurance: 1,000,000 erase/write cycles
  - Data retention: > 200 years
  - ESD protection: > 4000V
- Temperature Ranges Supported:
  - Industrial (I): -40°C to +85°C
  - Extended (E): -40°C to +125°C
- RoHS Compliant
- Automotive AEC-Q100 Qualified

### Pin Function Table

| Name                   | Function           |
|------------------------|--------------------|
| $\overline{\text{CS}}$ | Chip Select Input  |
| SO                     | Serial Data Output |
| $\overline{\text{WP}}$ | Write-Protect      |
| Vss                    | Ground             |
| SI                     | Serial Data Input  |
| SCK                    | Serial Clock Input |
| HOLD                   | Hold Input         |
| Vcc                    | Supply Voltage     |

### Description

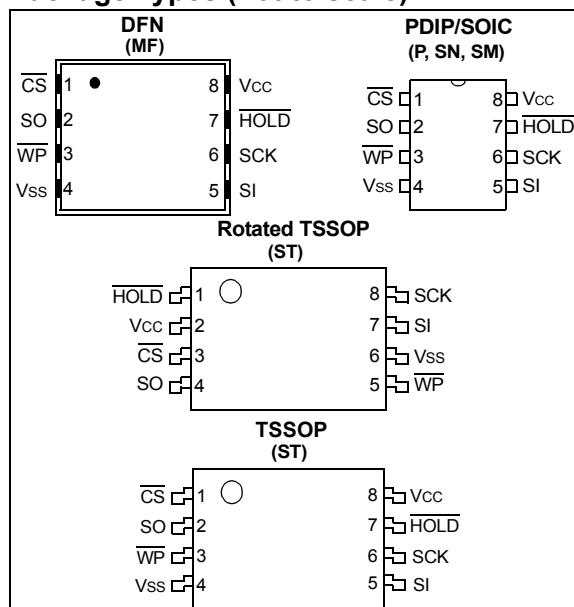
The Microchip Technology Inc. 25AA256/25LC256 (25XX256<sup>(1)</sup>) are 256 Kbit Serial Electrically Erasable PROMs. The memory is accessed via a simple Serial Peripheral Interface (SPI) compatible serial bus. The bus signals required are a clock input (SCK) plus separate data in (SI) and data out (SO) lines. Access to the device is controlled through a Chip Select (CS) input.

Communication to the device can be paused via the hold pin (HOLD). While the device is paused, transitions on its inputs will be ignored, with the exception of Chip Select, allowing the host to service higher priority interrupts.

The 25XX256 is available in standard packages including 8-lead PDIP and SOIC, and advanced packaging including 8-lead DFN and 8-lead TSSOP.

**Note 1:** 25XX256 is used in this document as a generic part number for the 25AA256/25LC256 devices.

### Package Types (not to scale)



## 1.0 ELECTRICAL CHARACTERISTICS

### Absolute Maximum Ratings (†)

|   |                                |
|---|--------------------------------|
| V <sub>CC</sub> .....                               | 6.5V                           |
| All inputs and outputs w.r.t. V <sub>SS</sub> ..... | -0.6V to V <sub>CC</sub> +1.0V |
| Storage temperature.....                            | -65°C to 150°C                 |
| Ambient temperature under bias.....                 | -40°C to 125°C                 |
| ESD protection on all pins.....                     | 4 kV                           |

† NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for an extended period of time may affect device reliability.

**TABLE 1-1: DC CHARACTERISTICS**

| DC CHARACTERISTICS |                       |   | Industrial (I): TA = -40°C to +85°C |                     | V <sub>CC</sub> = 1.8V to 5.5V |       | Extended (E): TA = -40°C to +125°C  |  | V <sub>CC</sub> = 1.8V to 5.5V |  |
|--------------------|-----------------------|---|-------------------------------------|---------------------|--------------------------------|-------|---|--|--------------------------------|--|
| Param. No.         | Sym.                  | Characteristic                                | Min.                                | Typ. <sup>(2)</sup> | Max.                           | Units | Test Conditions   |  |                                |  |
| D001               | V <sub>IH</sub>       | High-level input voltage                      | 0.7 V <sub>CC</sub>                 | —                   | V <sub>CC</sub> +1             | V     |   |  |                                |  |
| D002               | V <sub>IL</sub>       | Low-level input voltage                       | -0.3                                | —                   | 0.3 V <sub>CC</sub>            | V     | V <sub>CC</sub> ≥ 2.5V  |  |                                |  |
| D003               | V <sub>IL</sub>       |   | -0.3                                | —                   | 0.2 V <sub>CC</sub>            | V     | V <sub>CC</sub> < 2.5V  |  |                                |  |
| D004               | V <sub>OL</sub>       | Low-level output voltage                      | —                                   | —                   | 0.4                            | V     | I <sub>OL</sub> = 2.1 mA, V <sub>CC</sub> = 4.5V  |  |                                |  |
| D005               | V <sub>OL</sub>       |   | —                                   | —                   | 0.2                            | V     | I <sub>OL</sub> = 1.0 mA, V <sub>CC</sub> = 2.5V  |  |                                |  |
| D006               | V <sub>OH</sub>       | High-level output voltage                     | V <sub>CC</sub> -0.5                | —                   | —                              | V     | I <sub>OH</sub> = -400 μA   |  |                                |  |
| D007               | I <sub>LI</sub>       | Input leakage current                         | —                                   | —                   | ±1                             | μA    | $\overline{CS} = V_{CC}$ , V <sub>IN</sub> = V <sub>SS</sub> OR V <sub>CC</sub>             |  |                                |  |
| D008               | I <sub>LO</sub>       | Output leakage current                        | —                                   | —                   | ±1                             | μA    | $\overline{CS} = V_{CC}$ , V <sub>OUT</sub> = V <sub>SS</sub> OR V <sub>CC</sub>            |  |                                |  |
| D009               | C <sub>INT</sub>      | Internal Capacitance (all inputs and outputs) | —                                   | —                   | 7                              | pF    | T <sub>A</sub> = 25°C, F <sub>CLK</sub> = 1.0 MHz, V <sub>CC</sub> = 5.0V ( <b>Note 1</b> ) |  |                                |  |
| D010               | I <sub>CC</sub> Read  | Operating Current                             | —                                   | 2.5                 | 6                              | mA    | V <sub>CC</sub> = 5.5V; F <sub>CLK</sub> = 10.0 MHz; SO = Open                              |  |                                |  |
|                    |                       |   | —                                   | 0.5                 | 2.5                            | mA    | V <sub>CC</sub> = 2.5V; F <sub>CLK</sub> = 5.0 MHz; SO = Open                               |  |                                |  |
| D011               | I <sub>CC</sub> Write |   | —                                   | 0.6                 | 5                              | mA    | V <sub>CC</sub> = 5.5V  |  |                                |  |
|                    |                       |   | —                                   | 0.15                | 3                              | mA    | V <sub>CC</sub> = 2.5V  |  |                                |  |
| D012               | I <sub>CCS</sub>      | Standby Current                               | —                                   | 0.1                 | 5                              | μA    | $\overline{CS} = V_{CC} = 5.5V$ , Inputs tied to V <sub>CC</sub> or V <sub>SS</sub> , 125°C |  |                                |  |
|                    |                       |   | —                                   |                     | 1                              | μA    | $\overline{CS} = V_{CC} = 5.5V$ , Inputs tied to V <sub>CC</sub> or V <sub>SS</sub> , 85°C  |  |                                |  |

**Note 1:** This parameter is periodically sampled and not 100% tested.

**2:** Typical measurements taken at room temperature (25°C).

**TABLE 1-2: AC CHARACTERISTICS**

| AC CHARACTERISTICS |                  |                                     | Industrial (I): TA = -40°C to +85°C |      |       | VCC = 1.8V to 5.5V                |  |  |
|--------------------|------------------|-------------------------------------|-------------------------------------|------|-------|-----------------------------------|--|--|
|                    |                  |                                     | Extended (E): TA = -40°C to +125°C  |      |       | VCC = 1.8V to 5.5V                |  |  |
| Param. No.         | Sym.             | Characteristic                      | Min.                                | Max. | Units | Test Conditions                   |  |  |
| 1                  | FCLK             | Clock Frequency                     | —                                   | 10   | MHz   | 4.5V ≤ VCC ≤ 5.5V                 |  |  |
|                    |                  |                                     | —                                   | 5    | MHz   | 2.5V ≤ VCC < 4.5V                 |  |  |
|                    |                  |                                     | —                                   | 3    | MHz   | 1.8V ≤ VCC < 2.5V                 |  |  |
| 2                  | T <sub>CSS</sub> | $\overline{\text{CS}}$ Setup Time   | 50                                  | —    | ns    | 4.5V ≤ VCC ≤ 5.5V                 |  |  |
|                    |                  |                                     | 100                                 | —    | ns    | 2.5V ≤ VCC < 4.5V                 |  |  |
|                    |                  |                                     | 150                                 | —    | ns    | 1.8V ≤ VCC < 2.5V                 |  |  |
| 3                  | T <sub>CSH</sub> | $\overline{\text{CS}}$ Hold Time    | 100                                 | —    | ns    | 4.5V ≤ VCC ≤ 5.5V                 |  |  |
|                    |                  |                                     | 200                                 | —    | ns    | 2.5V ≤ VCC < 4.5V                 |  |  |
|                    |                  |                                     | 250                                 | —    | ns    | 1.8V ≤ VCC < 2.5V                 |  |  |
| 4                  | T <sub>CSD</sub> | $\overline{\text{CS}}$ Disable Time | 50                                  | —    | ns    | —                                 |  |  |
| 5                  | T <sub>SU</sub>  | Data Setup Time                     | 10                                  | —    | ns    | 4.5V ≤ VCC ≤ 5.5V                 |  |  |
|                    |                  |                                     | 20                                  | —    | ns    | 2.5V ≤ VCC < 4.5V                 |  |  |
|                    |                  |                                     | 30                                  | —    | ns    | 1.8V ≤ VCC < 2.5V                 |  |  |
| 6                  | T <sub>HD</sub>  | Data Hold Time                      | 20                                  | —    | ns    | 4.5V ≤ VCC ≤ 5.5V                 |  |  |
|                    |                  |                                     | 40                                  | —    | ns    | 2.5V ≤ VCC < 4.5V                 |  |  |
|                    |                  |                                     | 50                                  | —    | ns    | 1.8V ≤ VCC < 2.5V                 |  |  |
| 7                  | T <sub>R</sub>   | CLK Rise Time                       | —                                   | 100  | ns    | <b>(Note 1)</b>                   |  |  |
| 8                  | T <sub>F</sub>   | CLK Fall Time                       | —                                   | 100  | ns    | <b>(Note 1)</b>                   |  |  |
| 9                  | T <sub>HI</sub>  | Clock High Time                     | 50                                  | —    | ns    | 4.5V ≤ VCC ≤ 5.5V                 |  |  |
|                    |                  |                                     | 100                                 | —    | ns    | 2.5V ≤ VCC < 4.5V                 |  |  |
|                    |                  |                                     | 150                                 | —    | ns    | 1.8V ≤ VCC < 2.5V                 |  |  |
| 10                 | T <sub>LO</sub>  | Clock Low Time                      | 50                                  | —    | ns    | 4.5V ≤ VCC ≤ 5.5V                 |  |  |
|                    |                  |                                     | 100                                 | —    | ns    | 2.5V ≤ VCC < 4.5V                 |  |  |
|                    |                  |                                     | 150                                 | —    | ns    | 1.8V ≤ VCC < 2.5V                 |  |  |
| 11                 | T <sub>CLD</sub> | Clock Delay Time                    | 50                                  | —    | ns    | —                                 |  |  |
| 12                 | T <sub>CLE</sub> | Clock Enable Time                   | 50                                  | —    | ns    | —                                 |  |  |
| 13                 | T <sub>V</sub>   | Output Valid from Clock Low         | —                                   | 50   | ns    | 4.5V ≤ VCC ≤ 5.5V                 |  |  |
|                    |                  |                                     | —                                   | 100  | ns    | 2.5V ≤ VCC < 4.5V                 |  |  |
|                    |                  |                                     | —                                   | 160  | ns    | 1.8V ≤ VCC < 2.5V                 |  |  |
| 14                 | T <sub>HO</sub>  | Output Hold Time                    | 0                                   | —    | ns    | <b>(Note 1)</b>                   |  |  |
| 15                 | T <sub>DIS</sub> | Output Disable Time                 | —                                   | 40   | ns    | 4.5V ≤ VCC ≤ 5.5V <b>(Note 1)</b> |  |  |
|                    |                  |                                     | —                                   | 80   | ns    | 2.5V ≤ VCC < 4.5V <b>(Note 1)</b> |  |  |
|                    |                  |                                     | —                                   | 160  | ns    | 1.8V ≤ VCC ≤ 2.5V <b>(Note 1)</b> |  |  |
| 16                 | T <sub>HS</sub>  | $\overline{\text{HOLD}}$ Setup Time | 20                                  | —    | ns    | 4.5V ≤ VCC ≤ 5.5V                 |  |  |
|                    |                  |                                     | 40                                  | —    | ns    | 2.5V ≤ VCC < 4.5V                 |  |  |
|                    |                  |                                     | 80                                  | —    | ns    | 1.8V ≤ VCC < 2.5V                 |  |  |
| 17                 | T <sub>HH</sub>  | $\overline{\text{HOLD}}$ Hold Time  | 20                                  | —    | ns    | 4.5V ≤ VCC ≤ 5.5V                 |  |  |
|                    |                  |                                     | 40                                  | —    | ns    | 2.5V ≤ VCC < 4.5V                 |  |  |
|                    |                  |                                     | 80                                  | —    | ns    | 1.8V ≤ VCC < 2.5V                 |  |  |

**Note 1:** This parameter is periodically sampled and not 100% tested.

**2:** T<sub>WC</sub> begins on the rising edge of  $\overline{\text{CS}}$  after a valid write sequence and ends when the internal write cycle is complete.

**3:** This parameter is not tested but ensured by characterization. For endurance estimates in a specific application, please consult the Total Endurance™ Model which can be obtained from Microchip's website at [www.microchip.com](http://www.microchip.com).

**TABLE 1-2: AC CHARACTERISTICS (CONTINUED)**

| AC CHARACTERISTICS |      |   | Industrial (I): TA = -40°C to +85°C |      | VCC = 1.8V to 5.5V |                                     |
|--------------------|------|---|-------------------------------------|------|--------------------|-------------------------------------|
|                    |      |   | Extended (E): TA = -40°C to +125°C  |      | VCC = 1.8V to 5.5V |                                     |
| Param. No.         | Sym. | Characteristic                                | Min.                                | Max. | Units              | Test Conditions                     |
| 18                 | THZ  | $\overline{\text{HOLD}}$ Low to Output High-Z | —                                   | 30   | ns                 | 4.5V ≤ VCC ≤ 5.5V ( <b>Note 1</b> ) |
|                    |      |   | —                                   | 60   | ns                 | 2.5V ≤ VCC < 4.5V ( <b>Note 1</b> ) |
|                    |      |   | —                                   | 160  | ns                 | 1.8V ≤ VCC < 2.5V ( <b>Note 1</b> ) |
| 19                 | THV  | $\overline{\text{HOLD}}$ High to Output Valid | —                                   | 30   | ns                 | 4.5V ≤ VCC ≤ 5.5V                   |
|                    |      |   | —                                   | 60   | ns                 | 2.5V ≤ VCC < 4.5V                   |
|                    |      |   | —                                   | 160  | ns                 | 1.8V ≤ VCC < 2.5V                   |
| 20                 | TWC  | Internal Write Cycle Time                     | —                                   | 5    | ms                 | ( <b>Note 2</b> )                   |
| 21                 | —    | Endurance                                     | 1M                                  | —    | E/W Cycles         | 25°C, VCC = 5.5V ( <b>Note 3</b> )  |

**Note 1:** This parameter is periodically sampled and not 100% tested.

**2:** TWC begins on the rising edge of  $\overline{\text{CS}}$  after a valid write sequence and ends when the internal write cycle is complete.

**3:** This parameter is not tested but ensured by characterization. For endurance estimates in a specific application, please consult the Total Endurance™ Model which can be obtained from Microchip's website at [www.microchip.com](http://www.microchip.com).

**TABLE 1-3: AC TEST CONDITIONS**

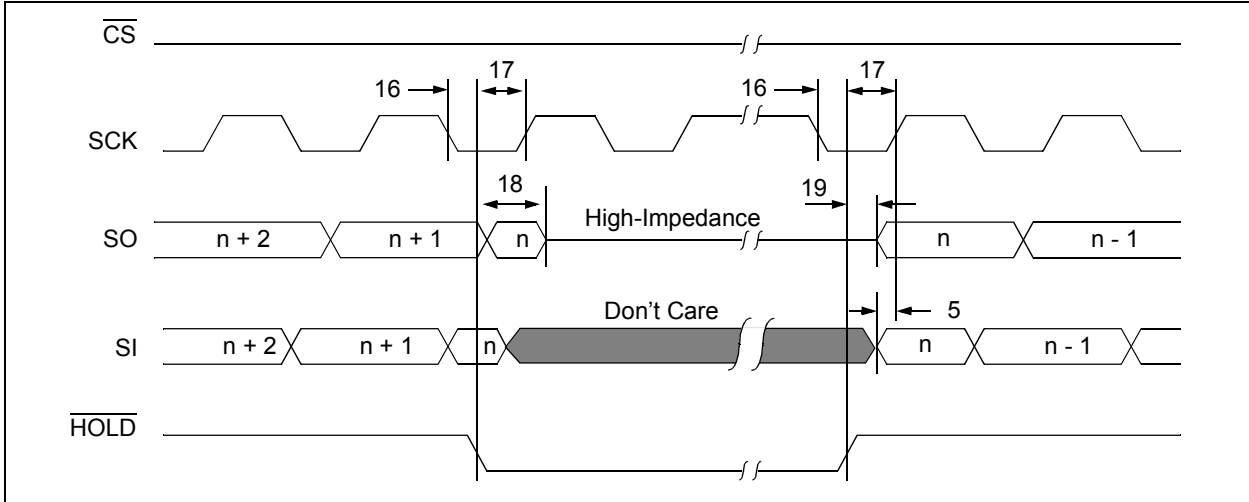
| AC Waveform:                       |                   |
|------------------------------------|-------------------|
| VLO = 0.2V                         | —                 |
| VHI = VCC – 0.2V                   | ( <b>Note 1</b> ) |
| VHI = 4.0V                         | ( <b>Note 2</b> ) |
| CL = 50 pF                         | —                 |
| Timing Measurement Reference Level |                   |
| Input                              | 0.5 VCC           |
| Output                             | 0.5 VCC           |

**Note 1:** For VCC ≤ 4.0V

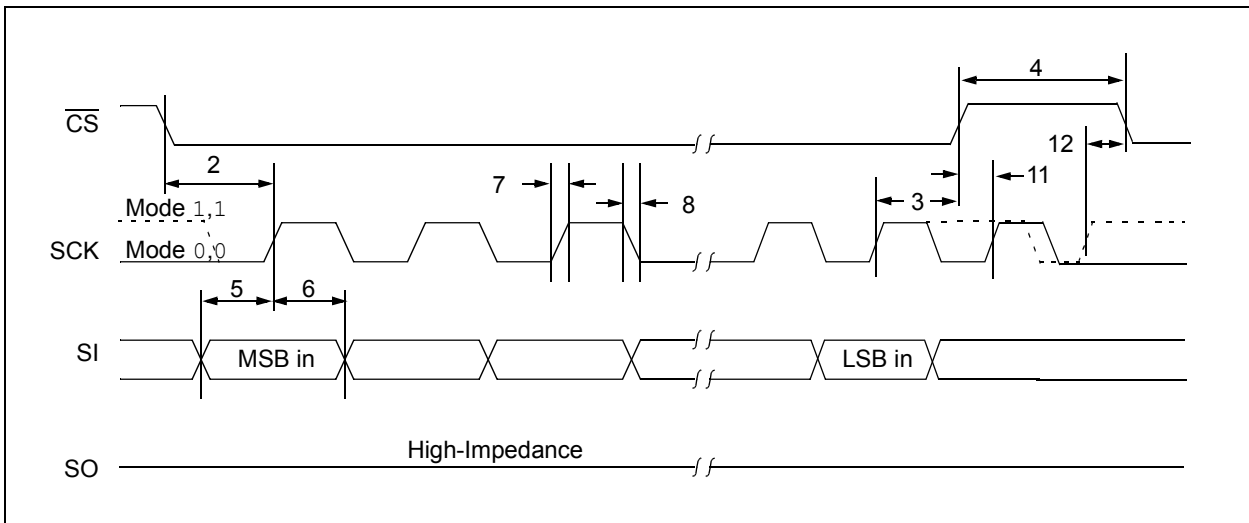
**2:** For VCC > 4.0V



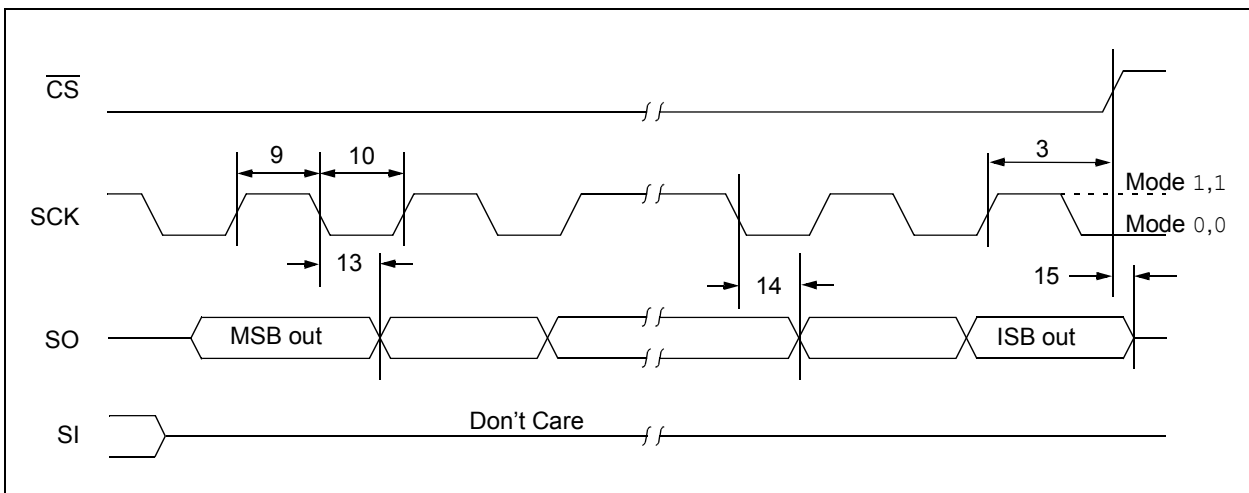
**FIGURE 1-1: HOLD TIMING**



**FIGURE 1-2: SERIAL INPUT TIMING**



**FIGURE 1-3: SERIAL OUTPUT TIMING**



## 2.0 FUNCTIONAL DESCRIPTION

### 2.1 Principles of Operation

The 25XX256 is a 32,768-byte Serial EEPROM designed to interface directly with the Serial Peripheral Interface (SPI) port of many of today's popular microcontroller families, including Microchip's PIC<sup>®</sup> microcontrollers. It may also interface with microcontrollers that do not have a built-in SPI port by using discrete I/O lines programmed properly in firmware to match the SPI protocol.

The 25XX256 contains an 8-bit instruction register. The device is accessed via the SI pin, with data being clocked in on the rising edge of SCK. The  $\overline{CS}$  pin must be low and the HOLD pin must be high for the entire operation.

Table 2-1 contains a list of the possible instruction bytes and format for device operation. All instructions, addresses, and data are transferred MSB first, LSB last.

Data (SI) is sampled on the first rising edge of SCK after  $\overline{CS}$  goes low. If the clock line is shared with other peripheral devices on the SPI bus, the user can assert the HOLD input and place the 25XX256 in 'HOLD' mode. After releasing the  $\overline{HOLD}$  pin, operation will resume from the point when the  $\overline{HOLD}$  was asserted.

### 2.2 Read Sequence

The device is selected by pulling  $\overline{CS}$  low. The 8-bit READ instruction is transmitted to the 25XX256 followed by the 16-bit address, with the first MSB of the address being a "don't care" bit. After the correct READ instruction and address are sent, the data stored in the memory at the selected address is shifted out on the SO pin. The data stored in the memory at the next address can be read sequentially by continuing to provide clock pulses. The internal Address Pointer is automatically incremented to the next higher address after each byte of data is shifted out. When the highest address is reached (7FFFh), the address counter rolls over to address 0000h allowing the read cycle to be continued indefinitely. The read operation is terminated by raising the  $\overline{CS}$  pin (Figure 2-1).

### 2.3 Write Sequence

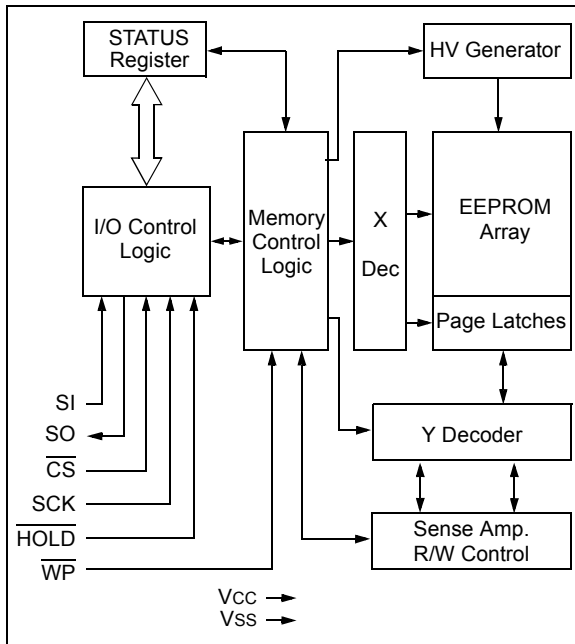
Prior to any attempt to write data to the 25XX256, the write enable latch must be set by issuing the  $\overline{WREN}$  instruction (Figure 2-4). This is done by setting  $\overline{CS}$  low and then clocking out the proper instruction into the 25XX256. After all eight bits of the instruction are transmitted, the  $\overline{CS}$  must be brought high to set the write enable latch. If the write operation is initiated immediately after the  $\overline{WREN}$  instruction without  $\overline{CS}$  being brought high, the data will not be written to the array because the write enable latch will not have been properly set.

Once the write enable latch is set, the user may proceed by setting the  $\overline{CS}$  low, issuing a  $\overline{WRITE}$  instruction, followed by the 16-bit address, with the first MSB of the address being a "don't care" bit, and then the data to be written. Up to 64 bytes of data can be sent to the device before a write cycle is necessary. The only restriction is that all of the bytes must reside in the same page.

**Note:** Page write operations are limited to writing bytes within a single physical page, **regardless** of the number of bytes actually being written. Physical page boundaries start at addresses that are integer multiples of the page buffer size (or 'page size') and, end at addresses that are integer multiples of page size - 1. If a page write command attempts to write across a physical page boundary, the result is that the data wraps around to the beginning of the current page (overwriting data previously stored there), instead of being written to the next page as might be expected. It is therefore necessary for the application software to prevent page write operations that would attempt to cross a page boundary.

For the data to be actually written to the array, the  $\overline{CS}$  must be brought high after the Least Significant bit (D0) of the  $n^{th}$  data byte has been clocked in. If  $\overline{CS}$  is brought high at any other time, the write operation will not be completed. Refer to Figure 2-2 and Figure 2-3 for more detailed illustrations on the byte write sequence and the page write sequence, respectively. While the write is in progress, the STATUS register may be read to check the status of the Write-in-process (WIP) bit (Figure 2-6). A read attempt of a memory array location will not be possible during a write cycle. When the write cycle is completed, the write enable latch is reset.

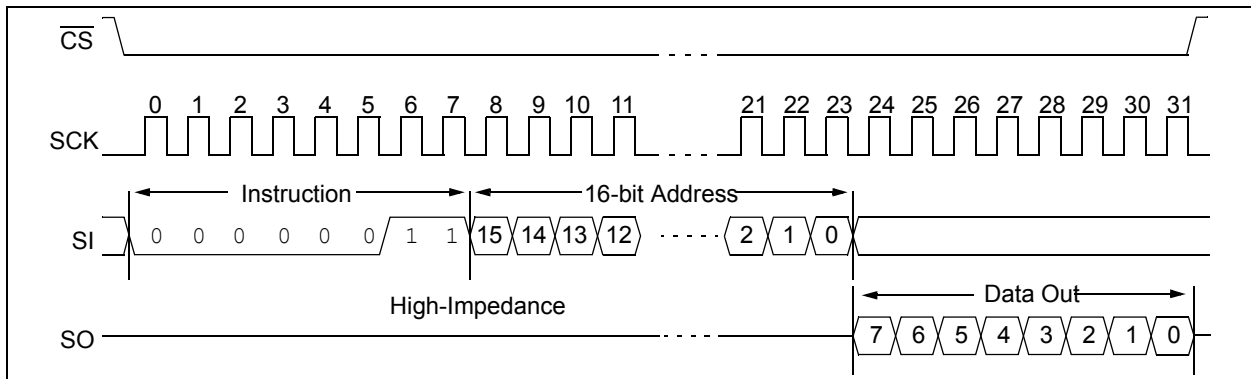
## BLOCK DIAGRAM



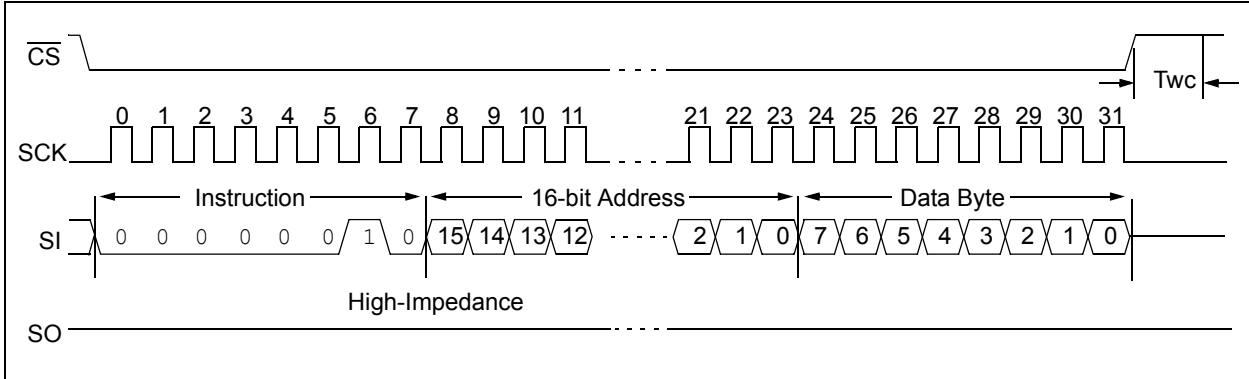
**TABLE 2-1: INSTRUCTION SET**

| Instruction Name | Instruction Format | Description   |
|------------------|--------------------|---|
| READ             | 0000 0011          | Read data from memory array beginning at selected address |
| WRITE            | 0000 0010          | Write data to memory array beginning at selected address  |
| WRDI             | 0000 0100          | Reset the write enable latch (disable write operations)   |
| WREN             | 0000 0110          | Set the write enable latch (enable write operations)      |
| RDSR             | 0000 0101          | Read STATUS register                                      |
| WRSR             | 0000 0001          | Write STATUS register                                     |

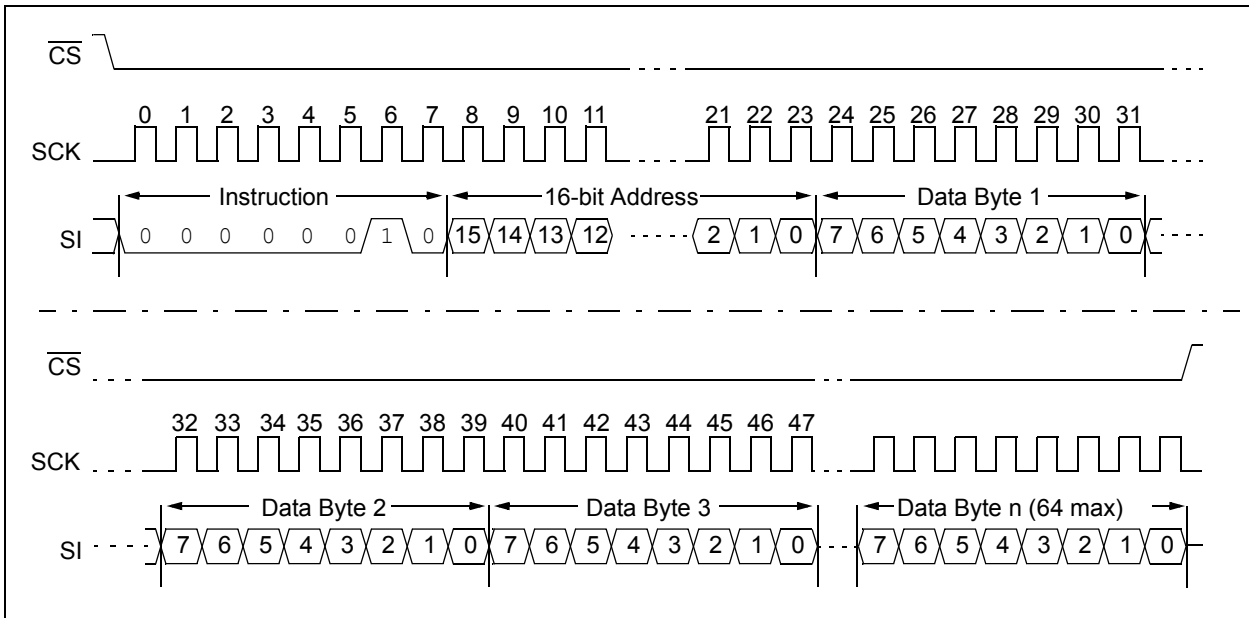
**FIGURE 2-1: READ SEQUENCE**



**FIGURE 2-2: BYTE WRITE SEQUENCE**



**FIGURE 2-3: PAGE WRITE SEQUENCE**



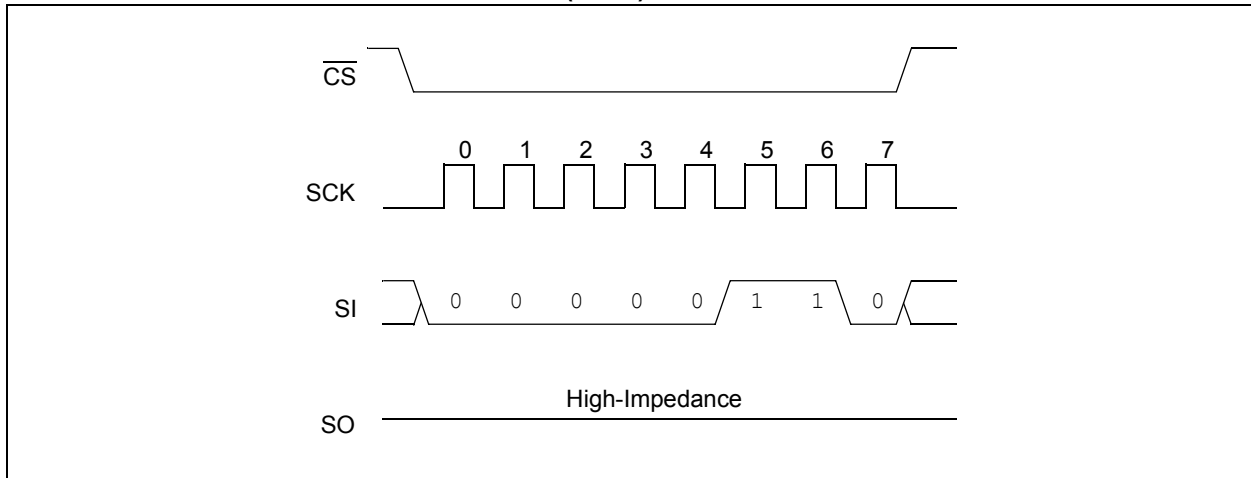
## 2.4 Write Enable ( $\overline{\text{WREN}}$ ) and Write Disable ( $\overline{\text{WRDI}}$ )

The 25XX256 contains a write enable latch. See [Table 2-1](#) for the Write-Protect Functionality Matrix. This latch must be set before any write operation will be completed internally. The  $\overline{\text{WREN}}$  instruction will set the latch, and the  $\overline{\text{WRDI}}$  will reset the latch.

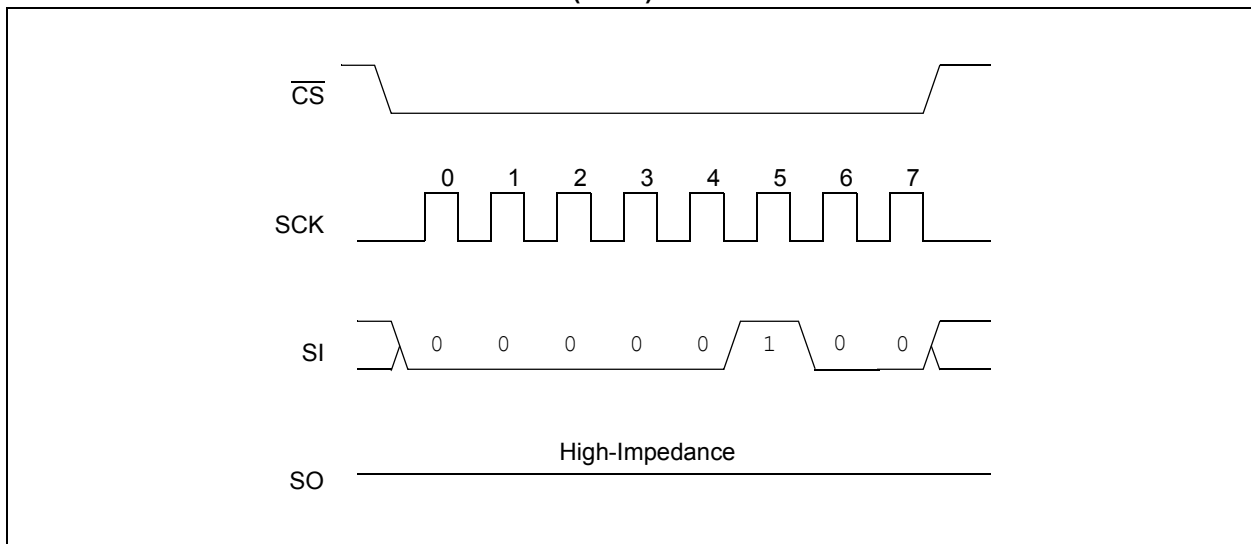
The following is a list of conditions under which the write enable latch will be reset:

- Power-up
- $\overline{\text{WRDI}}$  instruction successfully executed
- $\overline{\text{WRSR}}$  instruction successfully executed
- $\overline{\text{WRITE}}$  instruction successfully executed

**FIGURE 2-4: WRITE ENABLE SEQUENCE ( $\overline{\text{WREN}}$ )**



**FIGURE 2-5: WRITE DISABLE SEQUENCE ( $\overline{\text{WRDI}}$ )**



## 2.5 Read Status Register Instruction (RDSR)

The Read Status Register instruction (RDSR) provides access to the STATUS register. The STATUS register may be read at any time, even during a write cycle. The STATUS register is formatted as follows:

**TABLE 2-2: STATUS REGISTER**

|      |   |   |   |     |     |     |     |
|------|---|---|---|-----|-----|-----|-----|
| 7    | 6 | 5 | 4 | 3   | 2   | 1   | 0   |
| W/R  | - | - | - | W/R | W/R | R   | R   |
| WPEN | x | x | x | BP1 | BP0 | WEL | WIP |

W/R = writable/readable. R = read-only.

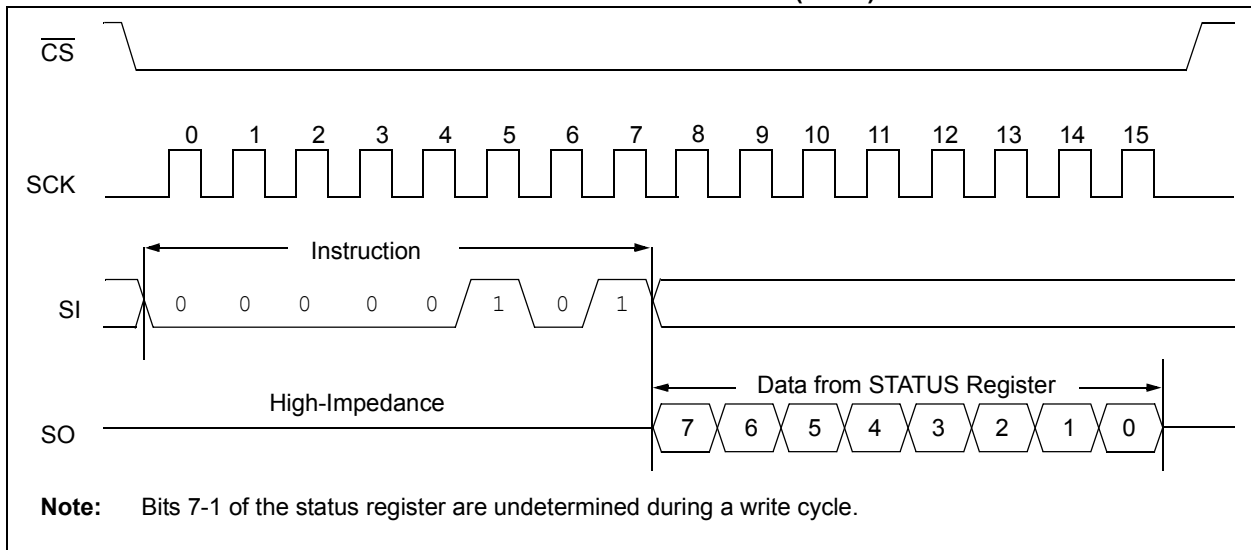
The **Write-In-Process (WIP)** bit indicates whether the 25XX256 is busy with a write operation. When set to a '1', a write is in progress, when set to a '0', no write is in progress. This bit is read-only.

The **Write Enable Latch (WEL)** bit indicates the status of the write enable latch and is read-only. When set to a '1', the latch allows writes to the array, when set to a '0', the latch prohibits writes to the array. The state of this bit can always be updated via the WREN or WRDI commands, regardless of the state of write protection on the STATUS register. These commands are shown in Figure 2-4 and Figure 2-5.

The **Block Protection (BP0 and BP1)** bits indicate which blocks are currently write-protected. These bits are set by the user issuing the WRSR instruction. These bits are nonvolatile, and are shown in Table 2-3.

See Figure 2-6 for the RDSR timing sequence.

**FIGURE 2-6: READ STATUS REGISTER TIMING SEQUENCE (RDSR)**



## 2.6 Write Status Register Instruction (WRSR)

The Write Status Register instruction ( $WRSR$ ) allows the user to write to the nonvolatile bits in the STATUS register as shown in Table 2-2. The user is able to select one of four levels of protection for the array by writing to the appropriate bits in the STATUS register. The array is divided up into four segments. The user has the ability to write-protect none, one, two, or all four of the segments of the array. The partitioning is controlled as shown in Table 2-3.

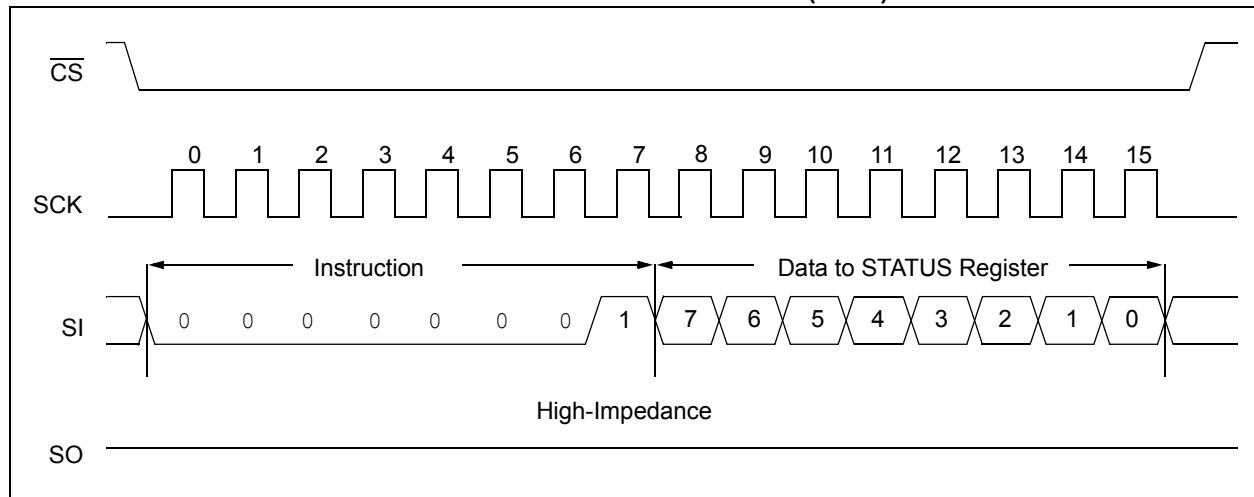
The Write-Protect Enable (WPEN) bit is a nonvolatile bit that is available as an enable bit for the  $\overline{WP}$  pin. The Write-Protect ( $\overline{WP}$ ) pin and the Write-Protect Enable (WPEN) bit in the STATUS register control the programmable hardware write-protect feature. Hardware write protection is enabled when  $\overline{WP}$  pin is low and the WPEN bit is high. Hardware write protection is disabled when either the  $\overline{WP}$  pin is high or the WPEN bit is low. When the chip is hardware write-protected, only writes to nonvolatile bits in the STATUS register are disabled. See Table 2-1 for a matrix of functionality on the WPEN bit.

See Figure 2-7 for the  $WRSR$  timing sequence.

TABLE 2-3: ARRAY PROTECTION

| BP1 | BP0 | Array Addresses Write-Protected |
|-----|-----|---------------------------------|
| 0   | 0   | none                            |
| 0   | 1   | upper 1/4<br>(6000h-7FFFh)      |
| 1   | 0   | upper 1/2<br>(4000h-7FFFh)      |
| 1   | 1   | all<br>(0000h-7FFFh)            |

FIGURE 2-7: WRITE STATUS REGISTER TIMING SEQUENCE ( $WRSR$ )



**Note:** An internal write cycle ( $T_{wc}$ ) is initiated on the rising edge of  $\overline{CS}$  after a valid write STATUS register sequence.

## 2.7 Data Protection

The following protection has been implemented to prevent inadvertent writes to the array:

- The write enable latch is reset on power-up
- A write enable instruction must be issued to set the write enable latch
- After a byte write, page write or STATUS register write, the write enable latch is reset
- $\overline{CS}$  must be set high after the proper number of clock cycles to start an internal write cycle
- Access to the array during an internal write cycle is ignored and programming is continued

## 2.8 Power-On State

The 25XX256 powers on in the following state:

- The device is in low-power Standby mode ( $\overline{CS} = 1$ )
- The write enable latch is reset
- SO is in high-impedance state
- A high-to-low-level transition on  $\overline{CS}$  is required to enter active state

**TABLE 2-1: WRITE-PROTECT FUNCTIONALITY MATRIX**

| WEL<br>(SR bit 1) | WPEN<br>(SR bit 7) | $\overline{WP}$ pin | Protected Blocks | Unprotected Blocks | STATUS Register |
|-------------------|--------------------|---------------------|------------------|--------------------|-----------------|
| 0                 | x                  | x                   | Protected        | Protected          | Protected       |
| 1                 | 0                  | x                   | Protected        | Writable           | Writable        |
| 1                 | 1                  | 0 (low)             | Protected        | Writable           | Protected       |
| 1                 | 1                  | 1 (high)            | Protected        | Writable           | Writable        |

x = don't care



## 3.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in [Table 3-1](#).

**TABLE 3-1: PIN FUNCTION TABLE**

| Name                     | PDIP/SOIC<br>TSSOP/DFN | Rotated<br>TSSOP | Function           |
|--------------------------|------------------------|------------------|--------------------|
| $\overline{\text{CS}}$   | 1                      | 3                | Chip Select Input  |
| SO                       | 2                      | 4                | Serial Data Output |
| $\overline{\text{WP}}$   | 3                      | 5                | Write-Protect Pin  |
| Vss                      | 4                      | 6                | Ground             |
| SI                       | 5                      | 7                | Serial Data Input  |
| SCK                      | 6                      | 8                | Serial Clock Input |
| $\overline{\text{HOLD}}$ | 7                      | 1                | Hold Input         |
| Vcc                      | 8                      | 2                | Supply Voltage     |

### 3.1 Chip Select ( $\overline{\text{CS}}$ )

A low level on this pin selects the device. A high level deselects the device and forces it into Standby mode. However, a programming cycle which is already initiated or in progress will be completed, regardless of the  $\overline{\text{CS}}$  input signal. If  $\overline{\text{CS}}$  is brought high during a program cycle, the device will go into Standby mode as soon as the programming cycle is complete. When the device is deselected, SO goes to the high-impedance state, allowing multiple parts to share the same SPI bus. A low-to-high transition on  $\overline{\text{CS}}$  after a valid write sequence initiates an internal write cycle. After power-up, a low level on  $\overline{\text{CS}}$  is required prior to any sequence being initiated.

### 3.2 Serial Output (SO)

The SO pin is used to transfer data out of the 25XX256. During a read cycle, data is shifted out on this pin after the falling edge of the serial clock.

### 3.3 Write-Protect ( $\overline{\text{WP}}$ )

This pin is used in conjunction with the WPEN bit in the STATUS register to prohibit writes to the nonvolatile bits in the STATUS register. When  $\overline{\text{WP}}$  is low and WPEN is high, writing to the nonvolatile bits in the STATUS register is disabled. All other operations function normally. When  $\overline{\text{WP}}$  is high, all functions, including writes to the nonvolatile bits in the STATUS register, operate normally. If the WPEN bit is set,  $\overline{\text{WP}}$  low during a STATUS register write sequence will disable writing to the STATUS register. If an internal write cycle has already begun,  $\overline{\text{WP}}$  going low will have no effect on the write.

The  $\overline{\text{WP}}$  pin function is blocked when the WPEN bit in the STATUS register is low. This allows the user to install the 25XX256 in a system with  $\overline{\text{WP}}$  pin grounded and still be able to write to the STATUS register. The WP pin functions will be enabled when the WPEN bit is set high.

### 3.4 Serial Input (SI)

The SI pin is used to transfer data into the device. It receives instructions, addresses and data. Data is latched on the rising edge of the serial clock.

### 3.5 Serial Clock (SCK)

The SCK is used to synchronize the communication between a master and the 25XX256. Instructions, addresses or data present on the SI pin are latched on the rising edge of the clock input, while data on the SO pin is updated after the falling edge of the clock input.

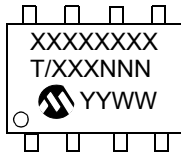
### 3.6 Hold ( $\overline{\text{HOLD}}$ )

The  $\overline{\text{HOLD}}$  pin is used to suspend transmission to the 25XX256 while in the middle of a serial sequence without having to retransmit the entire sequence again. It must be held high any time this function is not being used. Once the device is selected and a serial sequence is underway, the  $\overline{\text{HOLD}}$  pin may be pulled low to pause further serial communication without resetting the serial sequence. The  $\overline{\text{HOLD}}$  pin must be brought low while SCK is low, otherwise the HOLD function will not be invoked until the next SCK high-to-low transition. The 25XX256 must remain selected during this sequence. The SI, SCK and SO pins are in a high-impedance state during the time the device is paused and transitions on these pins will be ignored. To resume serial communication,  $\overline{\text{HOLD}}$  must be brought high while the SCK pin is low, otherwise serial communication will not resume. Lowering the  $\overline{\text{HOLD}}$  line at any time will tri-state the SO line.

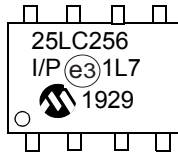
## 4.0 PACKAGING INFORMATION

### 4.1 Package Marking Information

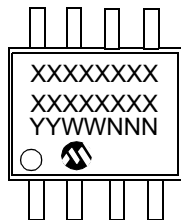
8-Lead PDIP



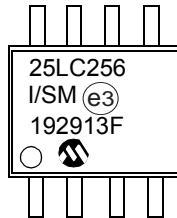
Example:



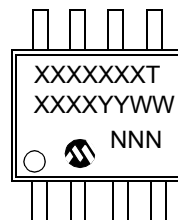
8-Lead SOIJ



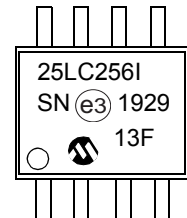
Example:



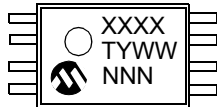
8-Lead SOIC



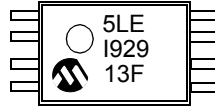
Example:



8-Lead TSSOP



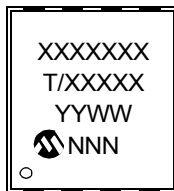
Example:



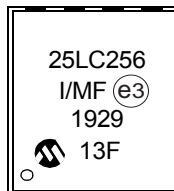
TSSOP 1st Line Marking Codes

| Device  | Standard | Rotated |
|---------|----------|---------|
| 25AA256 | 5AE      | 5AEX    |
| 25LC256 | 5LE      | 5LEX    |

8-Lead DFN



Example:



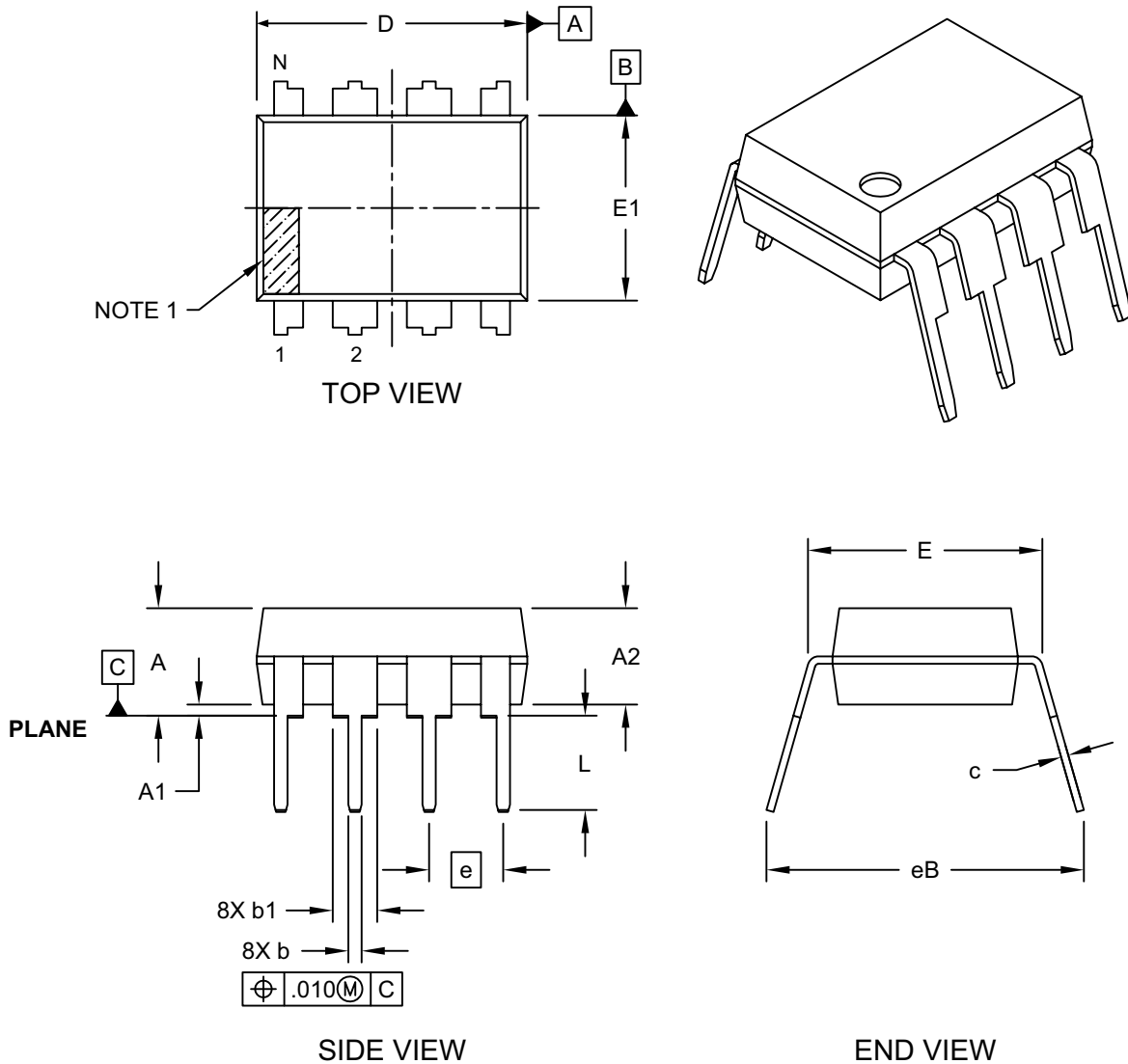
|                |        |  |
|----------------|--------|--|
| <b>Legend:</b> | XX...X | Part number or part number code                                  |
|                | T      | Temperature (I, E)   |
|                | Y      | Year code (last digit of calendar year)                          |
|                | YY     | Year code (last 2 digits of calendar year)                       |
|                | WW     | Week code (week of January 1 is week '01')                       |
|                | NNN    | Alphanumeric traceability code (2 characters for small packages) |
|                | (e3)   | RoHS-compliant JEDEC designator for Matte Tin (Sn)               |

**Note:** For very small packages with no room for the RoHS-compliant JEDEC designator (e3), the marking will only appear on the outer carton or reel label.

**Note:** In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

## 8-Lead Plastic Dual In-Line (P) - 300 mil Body [PDIP]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>

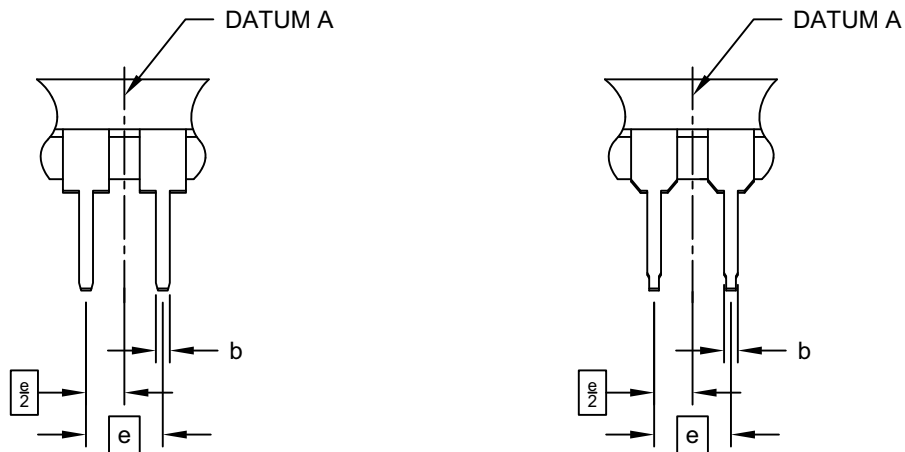


Microchip Technology Drawing No. C04-018-P Rev E Sheet 1 of 2

## 8-Lead Plastic Dual In-Line (P) - 300 mil Body [PDIP]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>

### ALTERNATE LEAD DESIGN (NOTE 5)



| Dimension Limits           | Units | INCHES   |      |      |
|----------------------------|-------|----------|------|------|
|                            |       | MIN      | NOM  | MAX  |
| Number of Pins             | N     | 8        |      |      |
| Pitch                      | e     | .100 BSC |      |      |
| Top to Seating Plane       | A     | -        | -    | .210 |
| Molded Package Thickness   | A2    | .115     | .130 | .195 |
| Base to Seating Plane      | A1    | .015     | -    | -    |
| Shoulder to Shoulder Width | E     | .290     | .310 | .325 |
| Molded Package Width       | E1    | .240     | .250 | .280 |
| Overall Length             | D     | .348     | .365 | .400 |
| Tip to Seating Plane       | L     | .115     | .130 | .150 |
| Lead Thickness             | c     | .008     | .010 | .015 |
| Upper Lead Width           | b1    | .040     | .060 | .070 |
| Lower Lead Width           | b     | .014     | .018 | .022 |
| Overall Row Spacing        | § eB  | -        | -    | .430 |

**Notes:**

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M  
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
5. Lead design above seating plane may vary, based on assembly vendor.

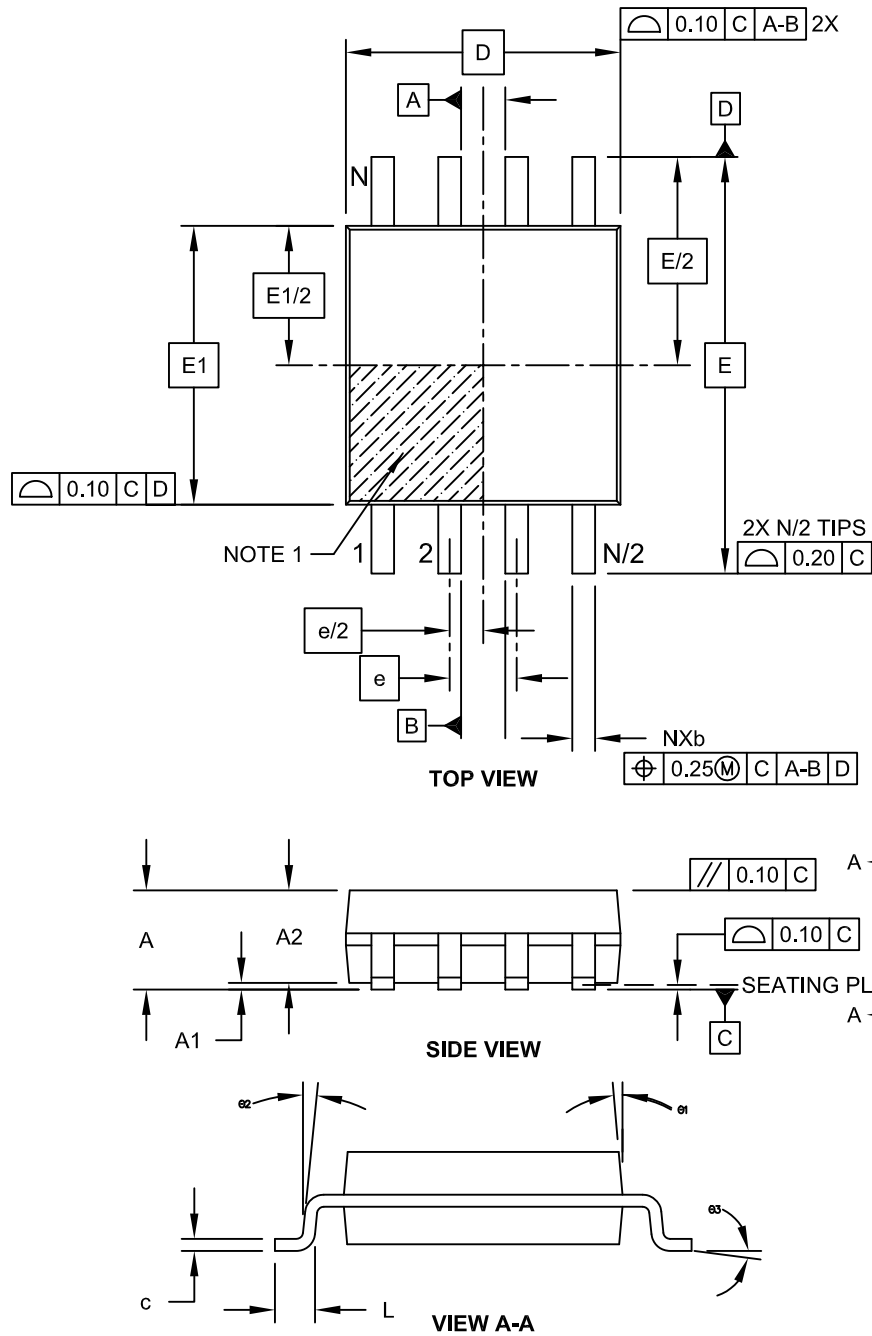
Microchip Technology Drawing No. C04-018-P Rev E Sheet 2 of 2

# 25AA256/25LC256

(JEITA/EIAJ Standard, Formerly called SOIC)

## 8-Lead Plastic Small Outline (SM) - Medium, 5.28 mm Body [SOIJ]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>

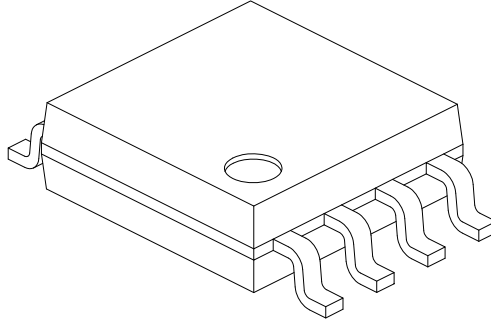


Microchip Technology Drawing C04-056C Sheet 1 of 2

# 25AA256/25LC256

## 8-Lead Plastic Small Outline (SM) - Medium, 5.28 mm Body [SOIJ]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



| Dimension Limits         | Units | MILLIMETERS |     |      |
|--------------------------|-------|-------------|-----|------|
|                          |       | MIN         | NOM | MAX  |
| Number of Pins           | N     | 8           |     |      |
| Pitch                    | e     | 1.27 BSC    |     |      |
| Overall Height           | A     | 1.77        | -   | 2.03 |
| Standoff §               | A1    | 0.05        |     | 0.25 |
| Molded Package Thickness | A2    | 1.75        | -   | 1.98 |
| Overall Width            | E     | 7.94 BSC    |     |      |
| Molded Package Width     | E1    | 5.25 BSC    |     |      |
| Overall Length           | D     | 5.26 BSC    |     |      |
| Foot Length              | L     | 0.51        | -   | 0.76 |
| Lead Thickness           | c     | 0.15        | -   | 0.25 |
| Lead Width               | b     | 0.36        | -   | 0.51 |
| Mold Draft Angle         | Ø1    | -           | -   | 15°  |
| Lead Angle               | Ø2    | 0°          | -   | 8°   |
| Foot Angle               | Ø3    | 0°          | -   | 8°   |

**Notes:**

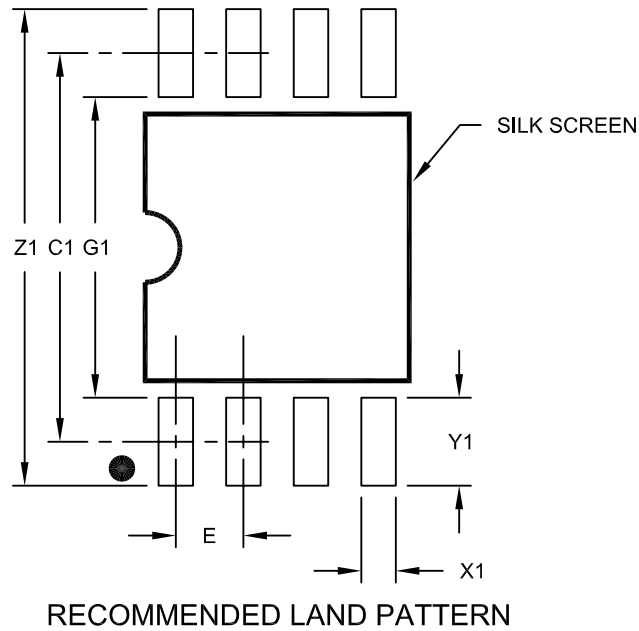
1. SOIJ, JEITA/EIAJ Standard, Formerly called SOIC
2. § Significant Characteristic
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25mm per side.

Microchip Technology Drawing No. C04-056C Sheet 2 of 2

# 25AA256/25LC256

## 8-Lead Plastic Small Outline (SM) - Medium, 5.28 mm Body [SOIJ]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



| Dimension Limits        | Units | MILLIMETERS |      |      |
|-------------------------|-------|-------------|------|------|
|                         |       | MIN         | NOM  | MAX  |
| Contact Pitch           | E     | 1.27 BSC    |      |      |
| Overall Width           | Z1    |             |      | 9.00 |
| Contact Pad Spacing     | C1    |             | 7.30 |      |
| Contact Pad Width (X8)  | X1    |             |      | 0.65 |
| Contact Pad Length (X8) | Y1    |             |      | 1.70 |
| Distance Between Pads   | G1    | 5.60        |      |      |
| Distance Between Pads   | G     | 0.62        |      |      |

**Notes:**

1. Dimensioning and tolerancing per ASME Y14.5M

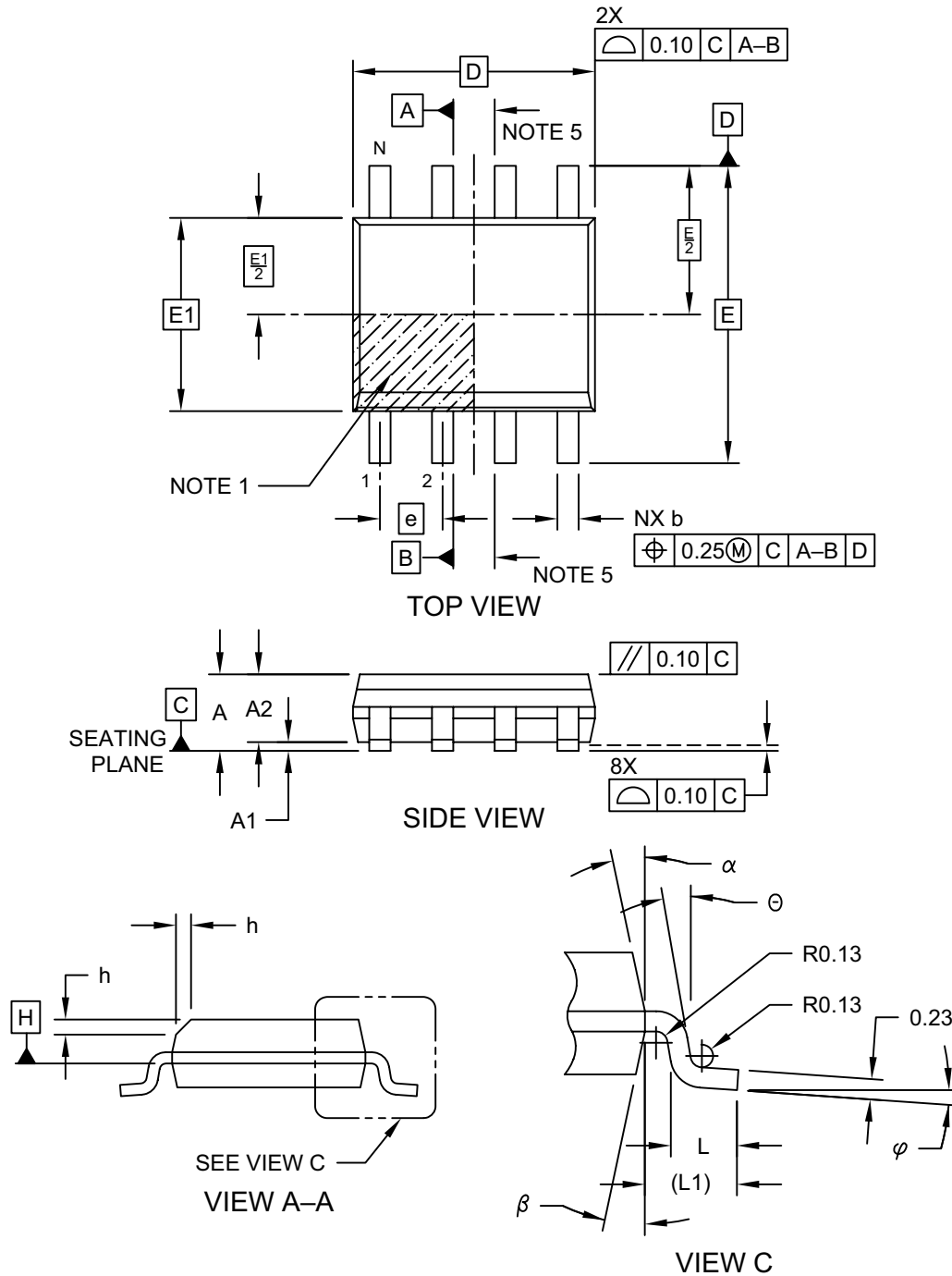
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2056C

# 25AA256/25LC256

## 8-Lead Plastic Small Outline (SN) - Narrow, 3.90 mm (.150 In.) Body [SOIC]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>

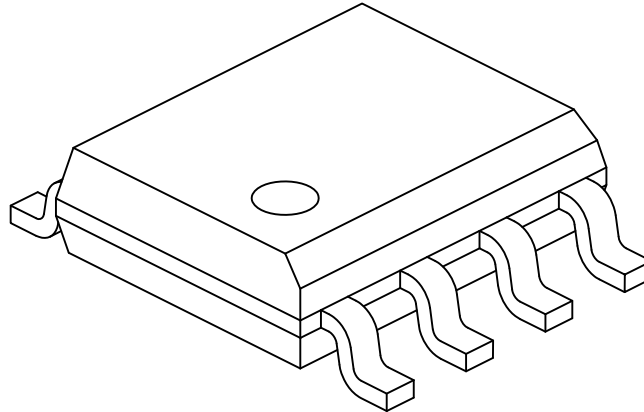


Microchip Technology Drawing No. C04-057-SN Rev E Sheet 1 of 2



## 8-Lead Plastic Small Outline (SN) - Narrow, 3.90 mm (.150 In.) Body [SOIC]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



| Dimension Limits         | Units    | MILLIMETERS |     |      |
|--------------------------|----------|-------------|-----|------|
|                          |          | MIN         | NOM | MAX  |
| Number of Pins           | N        | 8           |     |      |
| Pitch                    | e        | 1.27 BSC    |     |      |
| Overall Height           | A        | -           | -   | 1.75 |
| Molded Package Thickness | A2       | 1.25        | -   | -    |
| Standoff §               | A1       | 0.10        | -   | 0.25 |
| Overall Width            | E        | 6.00 BSC    |     |      |
| Molded Package Width     | E1       | 3.90 BSC    |     |      |
| Overall Length           | D        | 4.90 BSC    |     |      |
| Chamfer (Optional)       | h        | 0.25        | -   | 0.50 |
| Foot Length              | L        | 0.40        | -   | 1.27 |
| Footprint                | L1       | 1.04 REF    |     |      |
| Foot Angle               | $\phi$   | 0°          | -   | 8°   |
| Lead Thickness           | c        | 0.17        | -   | 0.25 |
| Lead Width               | b        | 0.31        | -   | 0.51 |
| Mold Draft Angle Top     | $\alpha$ | 5°          | -   | 15°  |
| Mold Draft Angle Bottom  | $\beta$  | 5°          | -   | 15°  |

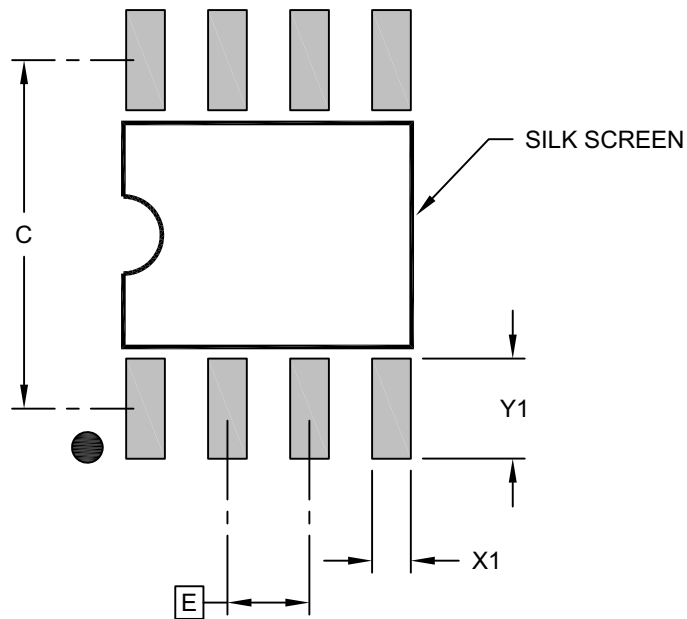
**Notes:**

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- § Significant Characteristic
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15mm per side.
- Dimensioning and tolerancing per ASME Y14.5M
  - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
  - REF: Reference Dimension, usually without tolerance, for information purposes only.
- Datums A & B to be determined at Datum H.

Microchip Technology Drawing No. C04-057-SN Rev E Sheet 2 of 2

## 8-Lead Plastic Small Outline (SN) - Narrow, 3.90 mm Body [SOIC]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

| Dimension Limits        | Units | MILLIMETERS |      |      |
|-------------------------|-------|-------------|------|------|
|                         |       | MIN         | NOM  | MAX  |
| Contact Pitch           | E     | 1.27 BSC    |      |      |
| Contact Pad Spacing     | C     |             | 5.40 |      |
| Contact Pad Width (X8)  | X1    |             |      | 0.60 |
| Contact Pad Length (X8) | Y1    |             |      | 1.55 |

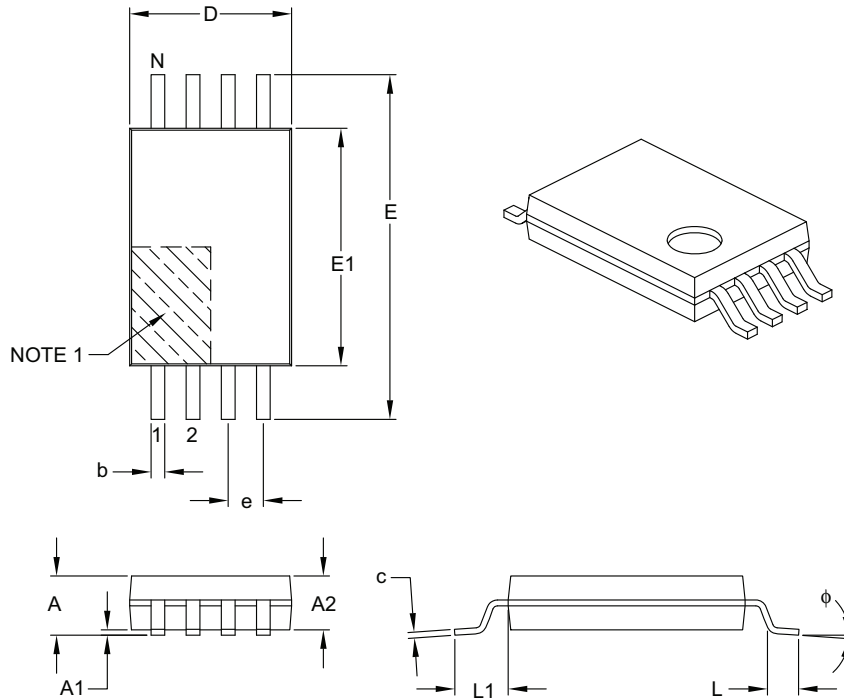
Notes:

1. Dimensioning and tolerancing per ASME Y14.5M  
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-2057-SN Rev E

## 8-Lead Plastic Thin Shrink Small Outline (ST) – 4.4 mm Body [TSSOP]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



| Dimension Limits         | Units  | MILLIMETERS |      |      |
|--------------------------|--------|-------------|------|------|
|                          |        | MIN         | NOM  | MAX  |
| Number of Pins           | N      | 8           |      |      |
| Pitch                    | e      | 0.65 BSC    |      |      |
| Overall Height           | A      | –           | –    | 1.20 |
| Molded Package Thickness | A2     | 0.80        | 1.00 | 1.05 |
| Standoff                 | A1     | 0.05        | –    | 0.15 |
| Overall Width            | E      | 6.40 BSC    |      |      |
| Molded Package Width     | E1     | 4.30        | 4.40 | 4.50 |
| Molded Package Length    | D      | 2.90        | 3.00 | 3.10 |
| Foot Length              | L      | 0.45        | 0.60 | 0.75 |
| Footprint                | L1     | 1.00 REF    |      |      |
| Foot Angle               | $\phi$ | 0°          | –    | 8°   |
| Lead Thickness           | c      | 0.09        | –    | 0.20 |
| Lead Width               | b      | 0.19        | –    | 0.30 |

**Notes:**

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M.

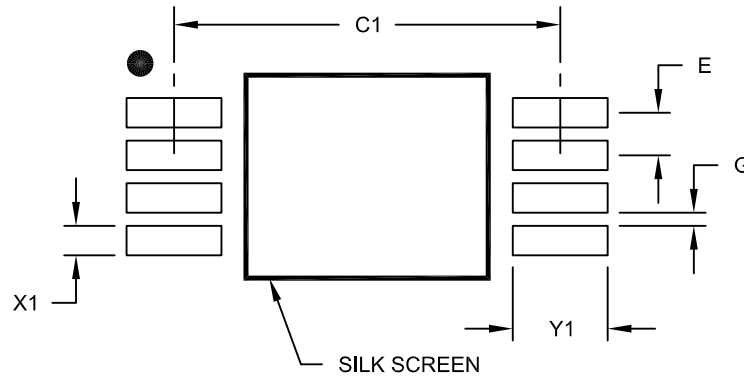
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-086B

## 8-Lead Plastic Thin Shrink Small Outline (ST) - 4.4 mm Body [TSSOP]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



### RECOMMENDED LAND PATTERN

| Dimension Limits        | Units | MILLIMETERS |      |      |
|-------------------------|-------|-------------|------|------|
|                         |       | MIN         | NOM  | MAX  |
| Contact Pitch           | E     | 0.65 BSC    |      |      |
| Contact Pad Spacing     | C1    |             | 5.90 |      |
| Contact Pad Width (X8)  | X1    |             |      | 0.45 |
| Contact Pad Length (X8) | Y1    |             |      | 1.45 |
| Distance Between Pads   | G     | 0.20        |      |      |

**Notes:**

1. Dimensioning and tolerancing per ASME Y14.5M

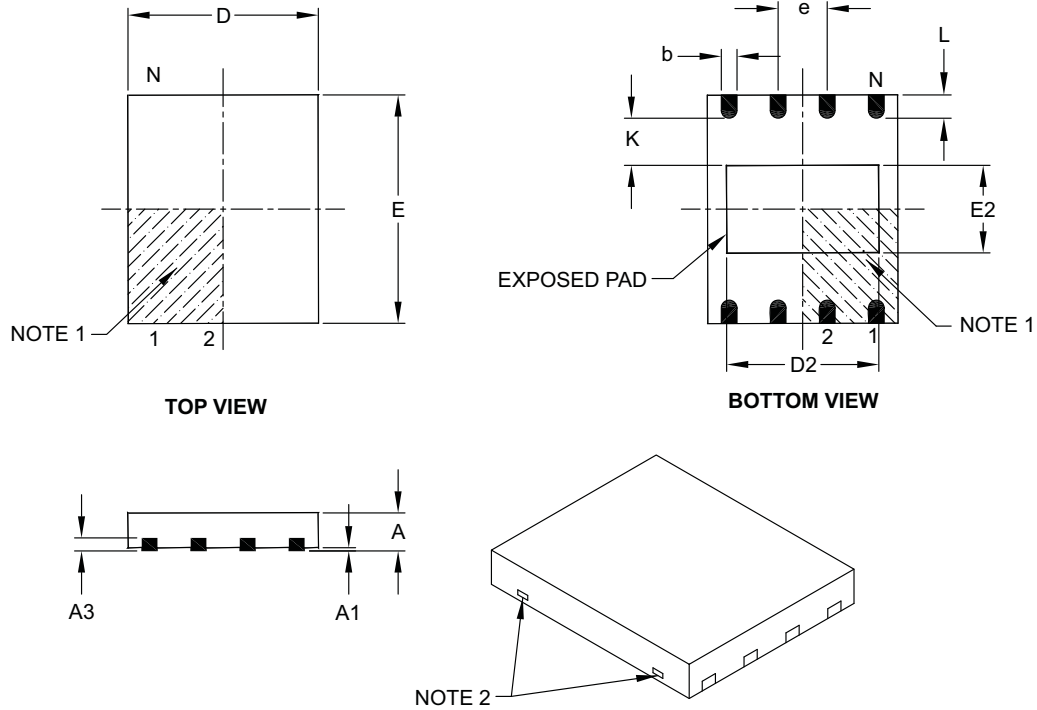
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2086A

# 25AA256/25LC256

## 8-Lead Plastic Dual Flat, No Lead Package (MF) – 6x5 mm Body [DFN-S]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



| Dimension Limits       | Units | MILLIMETERS |      |      |
|------------------------|-------|-------------|------|------|
|                        |       | MIN         | NOM  | MAX  |
| Number of Pins         | N     | 8           |      |      |
| Pitch                  | e     | 1.27 BSC    |      |      |
| Overall Height         | A     | 0.80        | 0.85 | 1.00 |
| Standoff               | A1    | 0.00        | 0.01 | 0.05 |
| Contact Thickness      | A3    | 0.20 REF    |      |      |
| Overall Length         | D     | 5.00 BSC    |      |      |
| Overall Width          | E     | 6.00 BSC    |      |      |
| Exposed Pad Length     | D2    | 3.90        | 4.00 | 4.10 |
| Exposed Pad Width      | E2    | 2.20        | 2.30 | 2.40 |
| Contact Width          | b     | 0.35        | 0.40 | 0.48 |
| Contact Length         | L     | 0.50        | 0.60 | 0.75 |
| Contact-to-Exposed Pad | K     | 0.20        | –    | –    |

**Notes:**

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Package may have one or more exposed tie bars at ends.
- Package is saw singulated.
- Dimensioning and tolerancing per ASME Y14.5M.

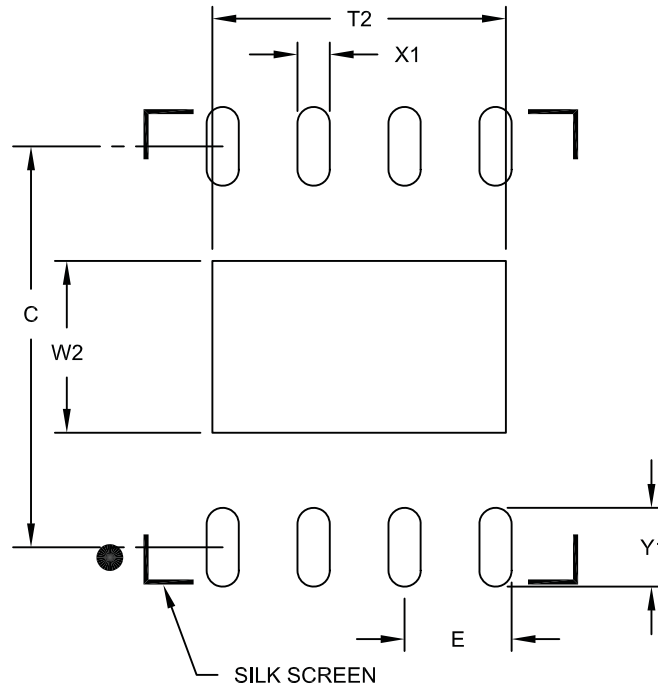
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

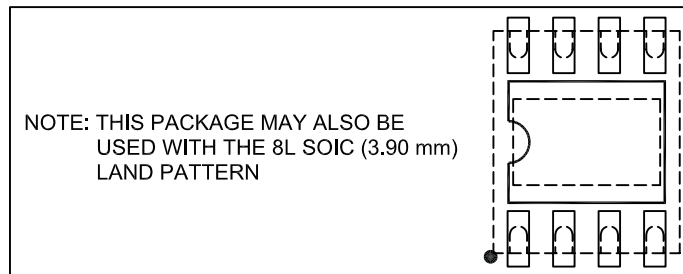
Microchip Technology Drawing C04-122B

## 8-Lead Plastic Dual Flat, No Lead Package (MF) - 6x5 mm Body [DFN-S]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN



| Units                      |    | MILLIMETERS |      |      |
|----------------------------|----|-------------|------|------|
| Dimension Limits           |    | MIN         | NOM  | MAX  |
| Contact Pitch              | E  | 1.27 BSC    |      |      |
| Optional Center Pad Width  | W2 |             |      | 2.40 |
| Optional Center Pad Length | T2 |             |      | 4.10 |
| Contact Pad Spacing        | C  |             | 5.60 |      |
| Contact Pad Width (X8)     | X1 |             |      | 0.45 |
| Contact Pad Length (X8)    | Y1 |             |      | 1.10 |

**Notes:**

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2122A

## APPENDIX A: REVISION HISTORY

### Revision H (08/2019)

Revise Product ID System, packages and notes; Clarified Extended E-Temp description; Update RoHS compliant description; Update PDIP package drawing.

### Revision G (01/2013)

Revise Automotive E Temp; Revise Table 1-2, Param. No. 21.

### Revision F (05/07)

Update Pb-free; Replace Package Drawings (Rev. AP); Update Product ID section.

### Revision E (08/05)

Remove Preliminary status. Revise Table 1-1, Params. D011 and D012.

### Revision D (06/05)

Update package information

### Revision C (11/03)

Corrections to Section 1.0, Electrical Characteristics.

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## PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

| <u>PART NO.</u>           |             | <u>X</u>  | - | <u>X</u> | <u>/XX</u> |
|---------------------------|-------------|---|---|----------|------------|
| Device                    | Tape & Reel | Temp Range  |   | Package  |            |
| <b>Device:</b>            | 25AA256     | 256k-bit, 1.8V, 64-Byte Page, SPI Serial EEPROM                           |   |          |            |
|                           | 25LC256     | 256k-bit, 2.5V, 64-Byte Page, SPI Serial EEPROM                           |   |          |            |
|                           | 25AA256X    | 256k-bit, 1.8V, 64-Byte Page, SPI Serial EEPROM, rotated pinout (ST only) |   |          |            |
|                           | 25LC256X    | 256k-bit, 2.5V, 64-Byte Page, SPI Serial EEPROM, rotated pinout (ST only) |   |          |            |
| <b>Tape &amp; Reel:</b>   | Blank       | = Standard packaging (tube)   |   |          |            |
|                           | T           | = Tape & Reel   |   |          |            |
| <b>Temperature Range:</b> | I           | = -40°C to +85°C (Industrial)   |   |          |            |
|                           | E           | = -40°C to +125°C (Extended)  |   |          |            |
| <b>Package:</b>           | P           | = Plastic DIP (300 mil body), 8-lead                                      |   |          |            |
|                           | SM          | = Plastic SOIJ (5.28 mm body), 8-lead                                     |   |          |            |
|                           | SN          | = Plastic SOIC (3.90 mm body), 8-lead                                     |   |          |            |
|                           | ST          | = TSSOP, 8-lead   |   |          |            |
|                           | MF          | = Micro Lead Frame (6 x 5 mm body), 8-lead                                |   |          |            |

### Examples:

- a) 25AA256T-I/SN = 256 kbit, 1.8V Serial EEPROM, Industrial temp., Tape & Reel, SOIC package
- b) 25AA256T-I/ST = 256 kbit, 1.8V Serial EEPROM, Industrial temp., Tape & Reel, TSSOP package
- c) 25LC256-I/P = 256 kbit, 2.5V Serial EEPROM, Industrial temp., P-DIP package
- d) 25LC256T-E/ST = 256 kbit, 2.5V Serial EEPROM, Extended temp., Tape & Reel, TSSOP package
- e) 25LC256XT-I/ST = 256 kbit, 2.5V Serial EEPROM, Industrial temp., Tape and Reel, Rotated TSSOP package
- f) 25AA256T-E/SM = 256 kbit, 1.8V Serial EEPROM, Extended temp., Tape and Reel, SOIJ package

- Note 1:** Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes only and is not printed on the device package. Check with your Microchip Sales Office for package availability with the Tape and Reel option.
- 2:** Contact Microchip for Automotive grade ordering part numbers.

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